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(54) COPPER FOIL, LAMINATE, AND FLEXIBLE PRINTED WIRING BOARD

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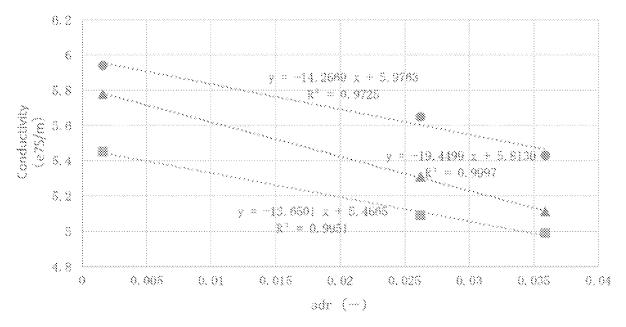
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(57)ABSTRACT

A copper foil, wherein at least one surface of the copper foil has a developed interfacial area ratio (sdr) of 0.0030 or less.



₩68GHz **&**81GHz **₩**107GHz